

200V N-Ch Power MOSFET

V_{DS}	200	V
$R_{DS(on),typ}$	28	m
I_D	50	A

Part Number	Package	Marking
HGD320N20S	TO-252	GD320N20S

Absolute Maximum Ratings at T_i	Symbol	Conditions	Value	Unit
Continuous Drain Current	I_D	T_C	50	A
		$T_C = 22$	35	A
		-	-	V
		-	-	V
Pulsed Drain Current	I	-	-	A
		E_{AS}	L=0.4mH, T_C	180
Power Dissipation	P_D	T_C	200	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 175	

Electrical Characteristics at T_j

Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250 A	200	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =250 A	2	3	4	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} =0V, V _{DS} =200V, T _j	-	-	1	A
		V _{GS} =0V, V _{DS} =200V, T _j 22	-	-	100	A
Gate to Source Leakage Current	I _{GSS}	V _{GS} 2 " V _{DS} =0V	-	-	100	nA
			-	28	32	m
Transconductance	g _{fs}	V _{DS} =5V, I _D =10A	-	31	-	S
Gate Resistance	R _G				-	

Dynamic Characteristics

Input Capacitance	C _{iss}		-	1598	-	
Output Capacitance	C _{oss}	V _{GS} =0V, V _{DS} =100V, f=1MHz	-	124	-	pF
Reverse Transfer Capacitance	C _{rss}		-	7.5	-	
Total Gate Charge	Q _g		-	19	-	
Gate to Source Charge	Q _{gs}	V _{DD} =100V, I _D =10A, V _{GS} =10V	-	7	-	nC
Gate to Drain (Miller) Charge	Q _{gd}		-	2	-	
Turn on Delay Time	t _{d(on)}		-	12	-	
Rise time		V _{DD} =100V, I _D =10A, V _{GS} =10V,	-	17	-	
Turn off Delay Time	t _{d(off)}	R _G =10 ,	-	23	-	ns
Fall Time	t _f		-	10	-	

Reverse Diode Characteristics

Diode Forward Voltage		V _{GS} =0V, I _F =10A	-			V
Reverse Recovery Time	t _{rr}		-	90	-	ns
Reverse Recovery Charge	Q _{rr}		-	306	-	nC

Gate Voltage

$I_D = 10A$

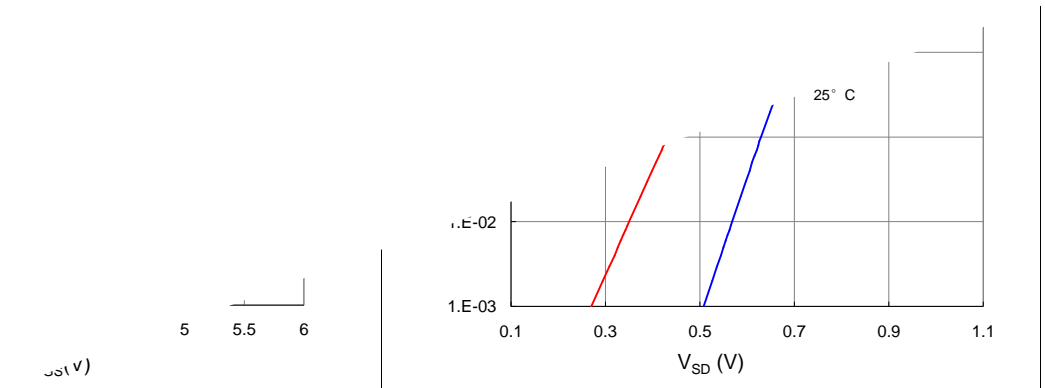
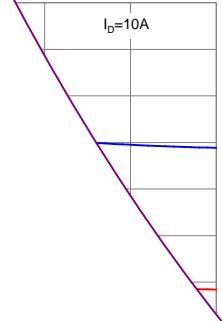


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

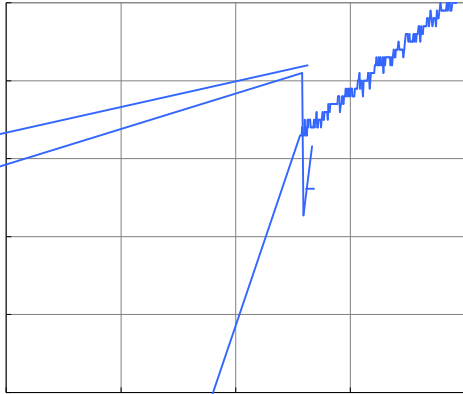


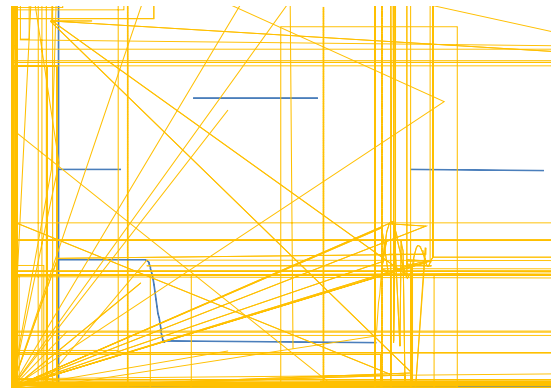
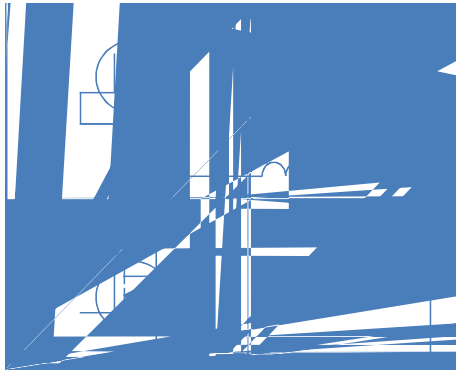
Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

Figure 9. Maximum Safe Operating Area

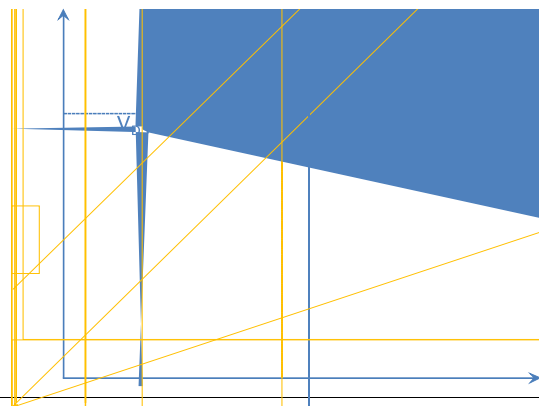
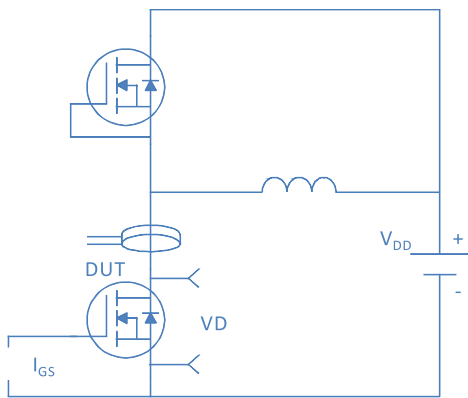
Figure 10. Maximum Drain Current vs. Case Temperature

Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case

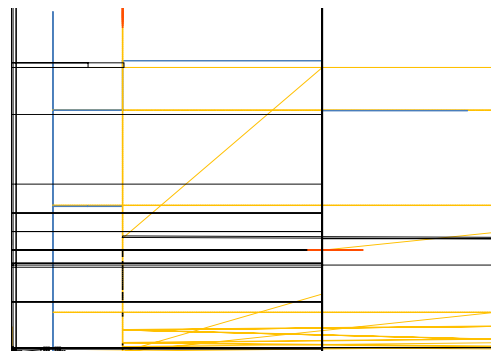
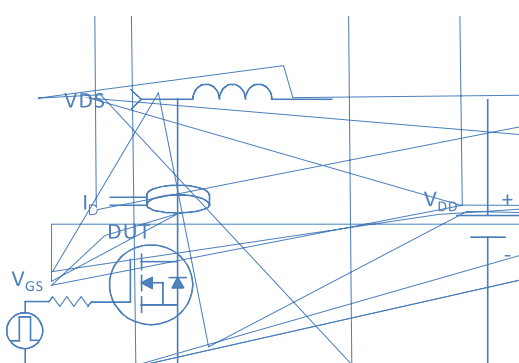
Inductive switching Test



Gate Charge Test



Uclamped Inductive Switching (UIS) Test



Diode Recovery Test

